**PATENT ASSIGNMENT**

Electronic Version v1.1  
Stylesheet Version v1.1

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<tr>
<th>SUBMISSION TYPE:</th>
<th>NEW ASSIGNMENT</th>
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<td>NATURE OF CONVEYANCE:</td>
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### CONVEYING PARTY DATA

<table>
<thead>
<tr>
<th>Name</th>
<th>Execution Date</th>
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<tbody>
<tr>
<td>Jui-Ching Hsieh</td>
<td>05/25/2009</td>
</tr>
<tr>
<td>Pin Chang</td>
<td>05/25/2009</td>
</tr>
<tr>
<td>Chung-De Chen</td>
<td>05/25/2009</td>
</tr>
<tr>
<td>Li-Chi Pan</td>
<td>05/04/2009</td>
</tr>
<tr>
<td>Yu-Jen Wang</td>
<td>05/25/2009</td>
</tr>
<tr>
<td>Chin-Horng Wang</td>
<td>05/05/2009</td>
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### RECEIVING PARTY DATA

<table>
<thead>
<tr>
<th>Name:</th>
<th>Industrial Technology Research Institute</th>
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</thead>
<tbody>
<tr>
<td>Street Address:</td>
<td>No. 195, Sec. 4, Chung Hsing Rd.</td>
</tr>
<tr>
<td>Internal Address:</td>
<td>Chutung</td>
</tr>
<tr>
<td>City:</td>
<td>Hsinchun</td>
</tr>
<tr>
<td>State/Country:</td>
<td>TAIWAN</td>
</tr>
<tr>
<td>Postal Code:</td>
<td>31040</td>
</tr>
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**PROPERTY NUMBERS Total: 1**

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<th>Property Type</th>
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<tr>
<td>Application Number:</td>
<td>12472359</td>
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### CORRESPONDENCE DATA

Fax Number: (949)660-0809  
*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*  
Email: usa@jcigrp.com.tw  
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**ATTORNEY DOCKET NUMBER:** 28694-US-PA  
**NAME OF SUBMITTER:** Belinda Lee
ASSIGNMENT

WHEREAS,

1. Hsieh, Jui-Ching
2. Chang, Pin
3. Chen, Chung-De
4. Pan, Li-Chi
5. Wang, Yu-Jen
6. Wang, Chin-Horng

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: CHIP PACKAGE STRUCTURE AND METHOD OF FABRICATING THE SAME

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hainchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be hold and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.
IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Jui Ching Haieh
Sole or First Joint Inventor: Haieh, Jui-Ching
Date: May 25, 2009

Signature: Pin Chang
Second Joint Inventor (if any): Chang, Pin
Date: May 25, 2009

Signature: Chung-De Chen
Third Joint Inventor (if any): Chen, Chung-De
Date: May 25, 2009

Signature: Li-Chi Pan
Fourth Joint Inventor (if any): Pan, Li-Chi
Date: 5/04/2009

Signature: Yu-Jen Wang
Fifth Joint Inventor (if any): Wang, Yu-Jen
Date: May 25, 2009

Signature: Chin-Horng Wang
Sixth Joint Inventor (if any): Wang, Chin-Horng
Date: 5/05/2009